

PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
Satoru KATSURAYAMA	04/29/2009
Tomoe YAMASHIRO	04/25/2009
Takashi HIRANO	04/13/2009
RECEIVING PARTY DATA	
Name:	SUMITOMO BAKELITE CO., LTD.
Street Address:	5-8, Higashi-Shinagawa 2-chome, Shinagawa-ku
City:	Tokyo
State/Country:	JAPAN
Postal Code:	140-0002
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	12447657
CORRESPONDENCE DATA	
Fax Number:	(703)519-9958
<i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i>	
Phone:	703-519-9953
Email:	mnakai@dcpatent.com
Correspondent Name:	Masayasu Mori
Address Line 1:	918 PRINCE STREET
Address Line 4:	Alexandria, VIRGINIA 22314
ATTORNEY DOCKET NUMBER:	01159_1022
NAME OF SUBMITTER:	Masayasu Mori
Total Attachments: 2 source=01159_1022_Assignment#page1.tif source=01159_1022_Assignment#page2.tif	

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PATENT
REEL: 023567 FRAME: 0774

ASSIGNMENT

In consideration of good and valuable consideration, the receipt of which is hereby acknowledged, we the undersigned, Satoru KATSURAYAMA, Tomoe YAMASHIRO and Takashi HIRANO, hereby sell, assign, and transfer to SUMITOMO BAKELITE CO., LTD., a corporation of Japan, having a principal place of business at 5-8, Higashi-Shinagawa 2-chome, Shinagawa-ku, Tokyo 140-0002 Japan ("Assignee"), and its successors, assigns, and legal representatives, the entire right, title, and interest for the United States and all foreign countries, in and to any and all improvements that are disclosed in the application for the United States patent, entitled:

ADHESIVE TAPE AND SEMICONDUCTOR DEVICE USING THE SAME

- ☒ which has been executed by the undersigned concurrently herewith,
☐ which was filed on _____ and assigned Serial No. _____

and in to said application and all divisional, continuing, substitute, renewal, reissue, and all other patent applications that have been or shall be filed in the United States and all foreign countries on any of said improvements; and in and to all original and reissued patents that have been or shall be issued in the United States and all foreign countries on said improvements; and in and to all rights of priority resulting from the filing of said United States application;

agree that said Assignee may apply for and receive a patent or patents for said improvements in its own name; and that, when requested, without charge to, but at the expense of, said Assignee, its successors, assigns, and legal representatives, to carry out in good faith the intent and purpose of this Assignment, the undersigned will execute all divisional, continuing, substitute, renewal, reissue, and all other patent applications on any and all said improvements; execute all assignments and powers of attorney; communicate to said Assignee, its successors, assigns, and representatives all facts known to the undersigned relating to said improvements and the history thereof; and generally assist said Assignee, its successors, assigns, or representatives in securing and maintaining proper patent protection for said improvements and for vesting title to said improvements, and all applications for patents and all patents on said improvements, in said Assignee, its successors, assigns, and legal representatives; and

covenant with said Assignee, its successors, assigns, and legal representatives that no assignment, grant, mortgage, license, or other agreement affecting the rights and property herein conveyed has been made to others by the undersigned, and that full right to convey the same as herein expressed is possessed by the undersigned.

Each Inventor: Please Sign and Date Below:

29 / 04, 2009
Date

Satoru Katsurayama
Name: Satoru KATSURAYAMA

Each Inventor: Please Sign and Date Below:

25 / 04, 2009
Date

Tomoe Yamashiro
Name: Tomoe YAMASHIRO

Each Inventor: Please Sign and Date Below:

13 / 04, 2009
Date

Takashi Hiran
Name: Takashi HIRANO